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# IPC-6012A with Amendment 1

Qualification and Performance

Specification for Rigid

Printed Boards

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#### INTERNATIONAL ELECTROTECHNICAL COMMISSION

#### QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARDS

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IPC-6012A with Amendment 1

# Qualification and Performance Specification for Rigid Printed Boards

Developed by the Rigid Board Performance Specifications Task Group (D-β3a) of the Rigid Printed Board Committee (D-30) of IPC

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Users of this standard are encouraged to participate in the development of future revisions.

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#### FOREWORD

This specification is intended to provide information on the detailed performance criteria of rigid printed boards. It supersedes IPC-RB-276 and IPC-6012 and was developed as a revision to those documents. The information contained herein is also intended to supplement the generic requirements identified in IPC-6011. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

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As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms located at the end of each document.

## Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the Rigid Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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